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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	6144
Number of Logic Elements/Cells	27648
Total RAM Bits	393216
Number of I/O	404
Number of Gates	1569178
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	560-LBGA Exposed Pad, Metal
Supplier Device Package	560-MBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv1000e-7bg560i

Dedicated Routing

Some classes of signal require dedicated routing resources to maximize performance. In the Virtex-E architecture, dedicated routing resources are provided for two classes of signal.

- Horizontal routing resources are provided for on-chip 3-state buses. Four partitionable bus lines are provided per CLB row, permitting multiple buses within a row, as shown in Figure 8.
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB.Global Clock Distribution Network
- DLL Location

Clock Routing

Clock Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex-E devices include two tiers of clock routing resources referred to as global and local clock routing resources.

- The global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The global nets can be driven only by global buffers. There are four global buffers, one for each global net.
- The local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These local resources are more flexible than the global resources since they are not restricted to routing only to clock pins.

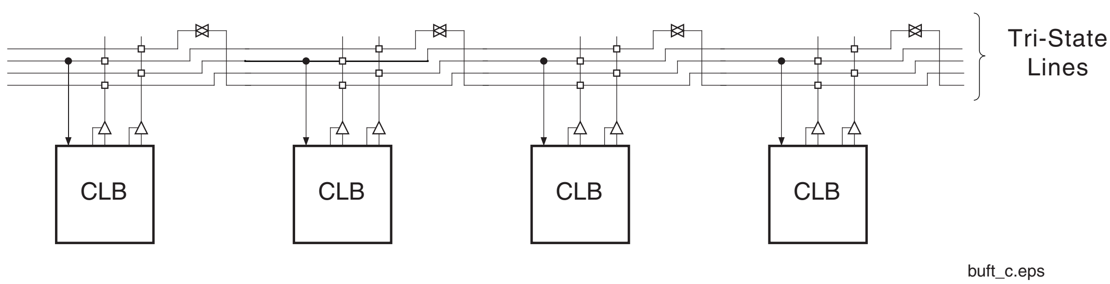

Figure 8: **BUFT Connections to Dedicated Horizontal Bus LInes**

Global Clock Distribution

Virtex-E provides high-speed, low-skew clock distribution through the global routing resources described above. A typical clock distribution net is shown in Figure 9.

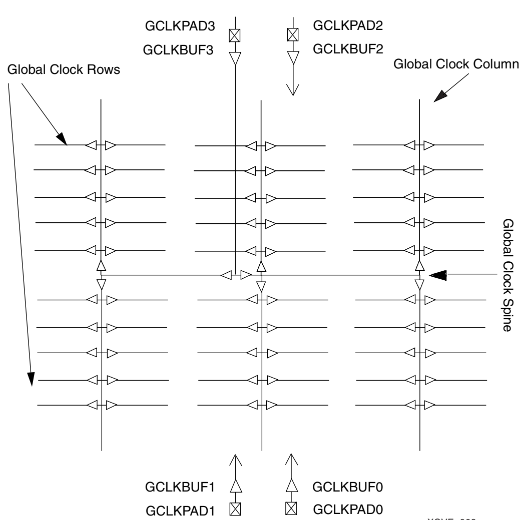

Figure 9: **Global Clock Distribution Network**

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is selected either from these pads or from signals in the general purpose routing.

Digital Delay-Locked Loops

There are eight DLLs (Delay-Locked Loops) per device, with four located at the top and four at the bottom, Figure 10. The DLLs can be used to eliminate skew between the clock input pad and the internal clock input pins throughout the device. Each DLL can drive two global clock networks.The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Additional delay is introduced such that clock edges arrive at internal flip-flops synchronized with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The DLL provides four quadrature phases of the source clock, and can double the clock or divide the clock by 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

Development System

Virtex-E FPGAs are supported by the Xilinx Foundation and Alliance Series CAE tools. The basic methodology for Virtex-E design consists of three interrelated steps: design entry, implementation, and verification. Industry-standard tools are used for design entry and simulation (for example, Synopsys FPGA Express), while Xilinx provides proprietary architecture-specific tools for implementation.

The Xilinx development system is integrated under the Xilinx Design Manager (XDM™) software, providing designers with a common user interface regardless of their choice of entry and verification tools. The XDM software simplifies the selection of implementation options with pull-down menus and on-line help.

Application programs ranging from schematic capture to Placement and Routing (PAR) can be accessed through the XDM software. The program command sequence is generated prior to execution, and stored for documentation.

Several advanced software features facilitate Virtex-E design. RPMs, for example, are schematic-based macros with relative location constraints to guide their placement. They help ensure optimal implementation of common functions.

For HDL design entry, the Xilinx FPGA Foundation development system provides interfaces to the following synthesis design environments.

- Synopsys (FPGA Compiler, FPGA Express)
- Exemplar (Spectrum)
- Synplicity (Synplify)

For schematic design entry, the Xilinx FPGA Foundation and Alliance development system provides interfaces to the following schematic-capture design environments.

- Mentor Graphics V8 (Design Architect, QuickSim II)
- Viewlogic Systems (Viewdraw)

Third-party vendors support many other environments.

A standard interface-file specification, Electronic Design Interchange Format (EDIF), simplifies file transfers into and out of the development system.

Virtex-E FPGAs are supported by a unified library of standard functions. This library contains over 400 primitives and macros, ranging from 2-input AND gates to 16-bit accumulators, and includes arithmetic functions, comparators, counters, data registers, decoders, encoders, I/O functions, latches, Boolean functions, multiplexers, shift registers, and barrel shifters.

The “soft macro” portion of the library contains detailed descriptions of common logic functions, but does not contain any partitioning or placement information. The performance of these macros depends, therefore, on the partitioning and placement obtained during implementation.

RPMs, on the other hand, do contain predetermined partitioning and placement information that permits optimal implementation of these functions. Users can create their own library of soft macros or RPMs based on the macros and primitives in the standard library.

The design environment supports hierarchical design entry, with high-level schematics that comprise major functional blocks, while lower-level schematics define the logic in these blocks. These hierarchical design elements are automatically combined by the implementation tools. Different design entry tools can be combined within a hierarchical design, thus allowing the most convenient entry method to be used for each portion of the design.

Design Implementation

The place-and-route tools (PAR) automatically provide the implementation flow described in this section. The partitioner takes the EDIF net list for the design and maps the logic into the architectural resources of the FPGA (CLBs and IOBs, for example). The placer then determines the best locations for these blocks based on their interconnections and the desired performance. Finally, the router interconnects the blocks.

The PAR algorithms support fully automatic implementation of most designs. For demanding applications, however, the user can exercise various degrees of control over the process. User partitioning, placement, and routing information is optionally specified during the design-entry process. The implementation of highly structured designs can benefit greatly from basic floor planning.

The implementation software incorporates Timing Wizard® timing-driven placement and routing. Designers specify timing requirements along entire paths during design entry. The timing path analysis routines in PAR then recognize these user-specified requirements and accommodate them.

Timing requirements are entered on a schematic in a form directly relating to the system requirements, such as the targeted clock frequency, or the maximum allowable delay between two registers. In this way, the overall performance of the system along entire signal paths is automatically tailored to user-generated specifications. Specific timing information for individual nets is unnecessary.

Design Verification

In addition to conventional software simulation, FPGA users can use in-circuit debugging techniques. Because Xilinx devices are infinitely reprogrammable, designs can be verified in real time without the need for extensive sets of software simulation vectors.

The development system supports both software simulation and in-circuit debugging techniques. For simulation, the system extracts the post-layout timing information from the design database, and back-annotates this information into the net list for use by the simulator. Alternatively, the user can verify timing-critical portions of the design using the TRCE® static timing analyzer.

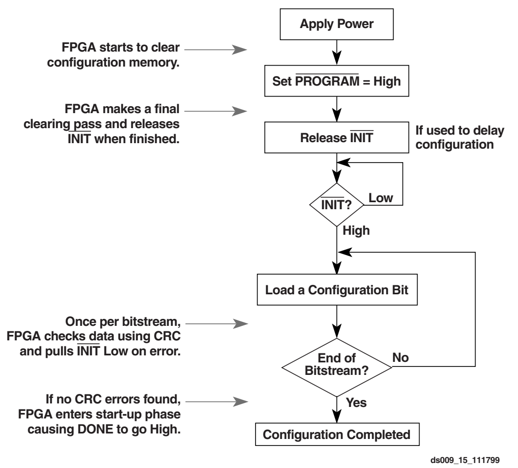

Figure 15: **Serial Configuration Flowchart**

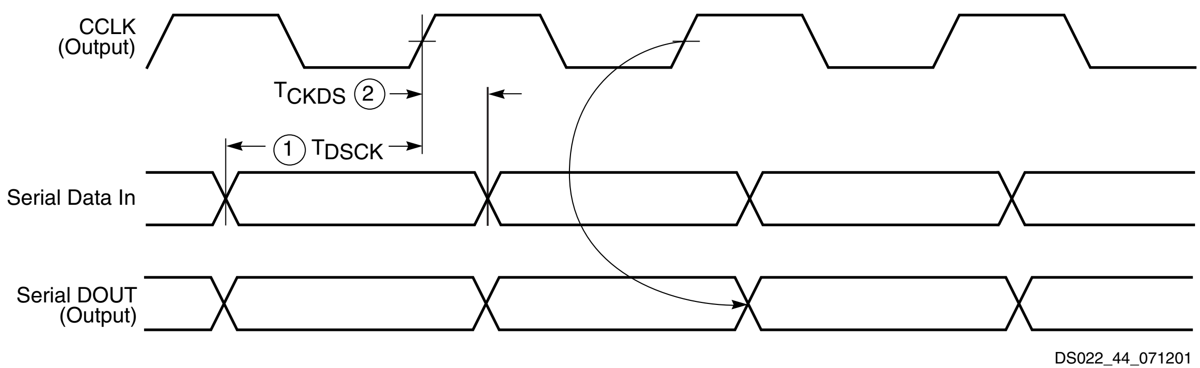

Figure 16: **Master-Serial Mode Programming Switching Characteristics**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling PROGRAM Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select (CS) signal and a Write signal (WRITE). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If WRITE is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, WRITE, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the CS pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of CS, illustrated in Figure 17.

1. Assert WRITE and CS Low. Note that when CS is asserted on successive CCLKs, WRITE must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while CS is Low and WRITE is High. Similarly, while WRITE is High, no more that one CS should be asserted.

ground. As the DLL delay taps reset to zero, glitches can occur on the DLL clock output pins. Activation of the RST pin can also severely affect the duty cycle of the clock output pins. Furthermore, the DLL output clocks no longer deskew with respect to one another. For these reasons, rarely use the reset pin unless re-configuring the device or changing the input frequency.

2x Clock Output — CLK2X

The output pin CLK2X provides a frequency-doubled clock with an automatic 50/50 duty-cycle correction. Until the CLKDLL has achieved lock, the CLK2X output appears as a 1x version of the input clock with a 25/75 duty cycle. This behavior allows the DLL to lock on the correct edge with respect to source clock. This pin is not available on the CLKDLLHF primitive.

Clock Divide Output — CLKDV

The clock divide output pin CLKDV provides a lower frequency version of the source clock. The CLKDV_DIVIDE property controls CLKDV such that the source clock is divided by N where N is either 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

This feature provides automatic duty cycle correction such that the CLKDV output pin always has a 50/50 duty cycle, with the exception of noninteger divides in HF mode, where the duty cycle is 1/3 for N=1.5 and 2/5 for N=2.5.

1x Clock Outputs — CLK[0|90|180|270]

The 1x clock output pin CLK0 represents a delay-compensated version of the source clock (CLKIN) signal. The CLKDLL primitive provides three phase-shifted versions of the CLK0 signal while CLKDLLHF provides only the 180 phase-shifted version. The relationship between phase shift and the corresponding period shift appears in Table 13.

Table 13: **Relationship of Phase-Shifted Output Clock to Period Shift**

Phase (degrees)	Period Shift (percent)
0	0%
90	25%
180	50%
270	75%

The timing diagrams in Figure 25 illustrate the DLL clock output characteristics.

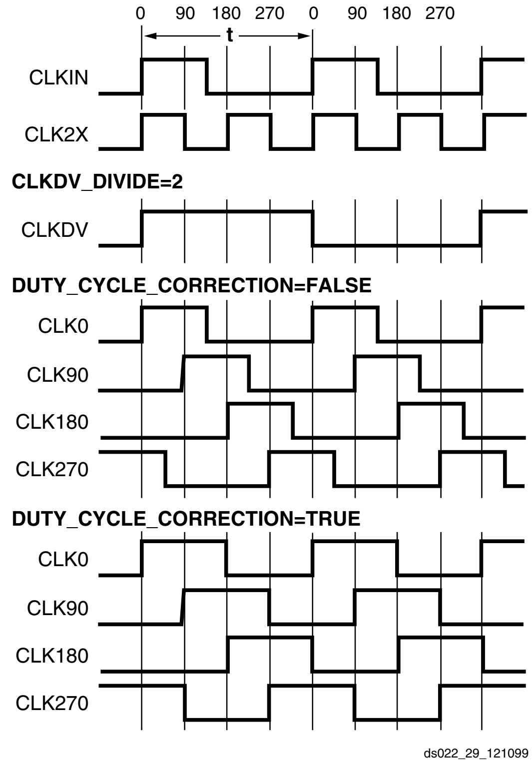

Figure 25: **DLL Output Characteristics**

The DLL provides duty cycle correction on all 1x clock outputs such that all 1x clock outputs by default have a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (TRUE by default), controls this feature. In order to deactivate the DLL duty cycle correction, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol. When duty cycle correction deactivates, the output clock has the same duty cycle as the source clock.

The DLL clock outputs can drive an OBUF, a BUFG, or they can route directly to destination clock pins. The DLL clock outputs can only drive the BUFGs that reside on the same edge (top or bottom).

Locked Output — LOCKED

To achieve lock, the DLL might need to sample several thousand clock cycles. After the DLL achieves lock, the LOCKED signal activates. The DLL timing parameter section of the data sheet provides estimates for locking times.

To guarantee that the system clock is established prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL locks. The STARTUP_WAIT property activates this feature.

Until the LOCKED signal activates, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement. In particular the CLK2X output appears as a 1x clock with a 25/75 duty cycle.

indicating that the block SelectRAM+ memory is now disabled. The DO bus retains the last value.

Dual Port Timing

Figure 34 shows a timing diagram for a true dual-port read/write block SelectRAM+ memory. The clock on port A has a longer period than the clock on Port B. The timing parameter T_{BCCS}, (clock-to-clock set-up) is shown on this diagram. The parameter, T_{BCCS} is violated once in the diagram. All other timing parameters are identical to the single port version shown in Figure 33.

T_{BCCS} is only of importance when the address of both ports are the same and at least one port is performing a write operation. When the clock-to-clock set-up parameter is violated for a WRITE-WRITE condition, the contents of the memory at that location are invalid. When the clock-to-clock set-up parameter is violated for a WRITE-READ condition, the contents of the memory are correct, but the read port has invalid data.

At the first rising edge of the CLKA, memory location 0x00 is to be written with the value 0xAAAA and is mirrored on the DOA bus. The last operation of Port B was a read to the same memory location 0x00. The DOB bus of Port B does not change with the new value on Port A, and retains the last read value. A short time later, Port B executes another read to memory location 0x00, and the DOB bus now reflects the new memory value written by Port A.

At the second rising edge of CLKA, memory location 0x7E is written with the value 0x9999 and is mirrored on the DOA bus. Port B then executes a read operation to the same memory location without violating the T_{BCCS} parameter and the DOB reflects the new memory values written by Port A.

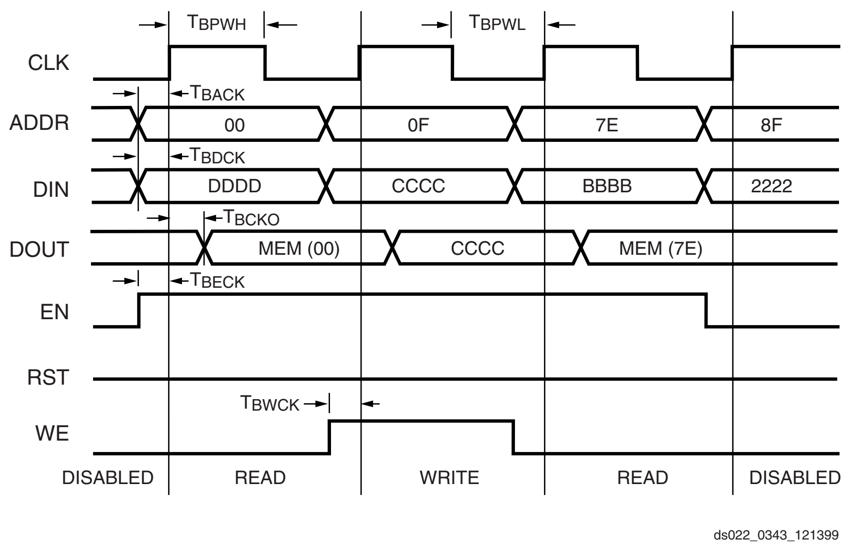

Figure 33: **Timing Diagram for Single Port Block SelectRAM+ Memory**

Table 21: **Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair *(Continued)***

Standard	Package		
	BGA, CS, FGA	HQ	PQ, TQ
HSTL Class I	18	13	9
HSTL Class III	9	7	5
HSTL Class IV	5	4	3
SSTL2 Class I	15	11	8
SSTL2 Class II	10	7	5
SSTL3 Class I	11	8	6
SSTL3 Class II	7	5	4
CTT	14	10	7
AGP	9	7	5

Note: This analysis assumes a 35 pF load for each output.

Table 22: **Virtex-E Equivalent Power/Ground Pairs**

Pkg/Part	XCV100E	XCV200E	XCV300E	XCV400E	XCV600E	XCV1000E	XCV1600E	XCV2000E
CS144	12	12						
PQ240	20	20	20	20				
HQ240					20	20		
BG352	20	32	32					
BG432			32	40	40			
BG560				40	40	56	58	60
FG256(1)	20	24	24					
FG456		40	40					
FG676				54	56			
FG680(2)					46	56	56	56
FG860						58	60	64
FG900					56	58		60
FG1156						96	104	120

Notes:
1. Virtex-E devices in FG256 packages have more V_{CCO} than Virtex series devices.
2. FG680 numbers are preliminary.

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at http://www.bourns.com.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectI/O library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

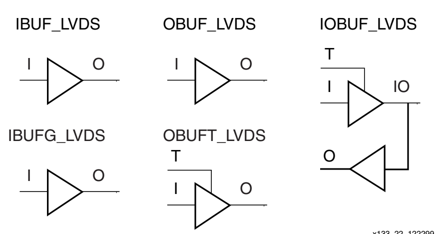

Figure 58: **LVDS elements**

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLKPAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

Pkg	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
	P	N	P	N	P	N	P	N
CS144	A6	C6	A7	B7	M7	M6	K7	N8
PQ240	P213	P215	P210	P209	P89	P87	P92	P93
HQ240	P213	P215	P210	P209	P89	P87	P92	P93
BG352	D14	A15	B14	A13	AF14	AD14	AE13	AC13
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG256	B8	A7	C9	A8	R8	T8	N8	N9
FG456	C11	B11	A11	D11	YII	AA11	W12	U12
FG676	E13	B13	C13	F14	AB13	AF13	AA14	AC14
FG680	A20	C22	D21	A19	AU22	AT22	AW19	AT21
FG860	C22	A22	B22	D22	AY22	AW21	BA22	AW20
FG900	C15	A15	E15	E16	AK16	AH16	AJ16	AF16
FG1156	E17	C17	D17	J18	AI19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

Table 43: **Output Library Macros**

Name	Inputs	Outputs
OBUFDS_FD_LVDS	D, C	O, OB
OBUFDS_FDE_LVDS	DD, CE, C	O, OB
OBUFDS_FDC_LVDS	D, C, CLR	O, OB
OBUFDS_FDCE_LVDS	D, CE, C, CLR	O, OB
OBUFDS_FDP_LVDS	D, C, PRE	O, OB
OBUFDS_FDPE_LVDS	D, CE, C, PRE	O, OB
OBUFDS_FDR_LVDS	D, C, R	O, OB
OBUFDS_FDRE_LVDS	D, CE, C, R	O, OB
OBUFDS_FDS_LVDS	D, C, S	O, OB
OBUFDS_FDSE_LVDS	D, CE, C, S	O, OB
OBUFDS_LD_LVDS	D, G	O, OB
OBUFDS_LDE_LVDS	D, GE, G	O, OB
OBUFDS_LDC_LVDS	D, G, CLR	O, OB
OBUFDS_LDCE_LVDS	D, GE, G, CLR	O, OB
OBUFDS_LDP_LVDS	D, G, PRE	O, OB
OBUFDS_LDPE_LVDS	D, GE, G, PRE	O, OB

Creating LVDS Output 3-State Buffers

LVDS output 3-state buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both output 3-state buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), 3-state (T), 3-state clock enable (TCE), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one High and one Low). If 3-state registers are used, they must be initialized to the same state. Failure to follow these rules leads to DRC errors in the software.

VHDL Instantiation

```
data0_p:   OBUFT_LVDS port map
(I=>data_int(0), T=>data_tri,
O=>data_p(0));

data0_inv: INV port map
(I=>data_int(0), O=>data_n_int(0));

data0_n:    OBUFT_LVDS port map
(I=>data_n_int(0), T=>data_tri,
O=>data_n(0));
```

Verilog Instantiation

```
OBUFT_LVDS data0_p   (.I(data_int[0]),
.T(data_tri), .O(data_p[0]));

INV        data0_inv (.I(data_int[0],
.O(data_n_int[0]);

OBUFT_LVDS data0_n   (.I(data_n_int[0]),
.T(data_tri), .O(data_n[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous 3-State Outputs

If the outputs are synchronous (registered in the IOB), then any IO_L#P|N pair can be used. If the outputs are asynchronous (no output register), then they must use one of the pairs that are part of the same IOB group at the end of a ROW or COLUMN in the device. This applies for either the 3-state pin or the data out pin.

LVDS pairs that can be used as asynchronous outputs are listed in the Virtex-E pinout tables. Some pairs are marked as “asynchronous capable” for all devices in that package, and others are marked as available only for that device in the package. If the device size might be changed at some point in the product lifetime, then only the common pairs for all packages should be used.

Adding Output and 3-State Registers

All LVDS buffers can have an output register in the IOB. The output registers must be in both the P-side and N-side IOBs. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The 3-state (T), 3-state clock enable (CE), clock pin (C), output clock enable (CE) and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
CTT	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.4	V_{REF} + 0.4	8	–8
AGP	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:
1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.
3. DC input and output levels for HSTL18 (HSTL I/O standard with V_{CCO} of 1.8 V) are provided in an HSTL white paper on **www.xilinx.com**.

LVDS DC Specifications

DC Parameter	Symbol	Conditions	Min	Typ	Max	Units
Supply Voltage	V_{CCO}		2.375	2.5	2.625	V
Output High Voltage for Q and $\overline{Q}$	V_{OH}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.25	1.425	1.6	V
Output Low Voltage for Q and $\overline{Q}$	V_{OL}	R_T = 100 Ω across Q and $\overline{Q}$ signals	0.9	1.075	1.25	V
Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{ODIFF}	R_T = 100 Ω across Q and $\overline{Q}$ signals	250	350	450	mV
Output Common-Mode Voltage	V_{OCM}	R_T = 100 Ω across Q and $\overline{Q}$ signals	1.125	1.25	1.375	V
Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	V_{IDIFF}	Common-mode input voltage = 1.25 V	100	350	NA	mV
Input Common-Mode Voltage	V_{ICM}	Differential input voltage = ±350 mV	0.2	1.25	2.2	V

Note: Refer to the Design Consideration section for termination schematics.

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under **LVPECL**, with a 100 Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	**3.0**		**3.3**		**3.6**		**V**
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3	-	0.3	-	0.3	-	V

Virtex-E Pin-to-Pin Output Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *with* DLL

Description(1)	Symbol	Device	Speed Grade(2, 3)				Units
			Min	-8	-7	-6	
LVTTL Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *with* DLL. For data *output* with different standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 10.	$T_{ICKOFDLL}$	XCV50E	1.0	3.1	3.1	3.1	ns
		XCV100E	1.0	3.1	3.1	3.1	ns
		XCV200E	1.0	3.1	3.1	3.1	ns
		XCV300E	1.0	3.1	3.1	3.1	ns
		XCV400E	1.0	3.1	3.1	3.1	ns
		XCV600E	1.0	3.1	3.1	3.1	ns
		XCV1000E	1.0	3.1	3.1	3.1	ns
		XCV1600E	1.0	3.1	3.1	3.1	ns
		XCV2000E	1.0	3.1	3.1	3.1	ns
		XCV2600E	1.0	3.1	3.1	3.1	ns
		XCV3200E	1.0	3.1	3.1	3.1	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load. For other I/O standards and different loads, see Table 3 and Table 4.
3. DLL output jitter is already included in the timing calculation.

Table 15: **BG560 Differential Pin Pair Summary XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
47	2	F4	C1	14	-
48	2	G5	E3	15	VREF
49	2	D2	G4	16	-
50	2	H5	E2	15	-
51	2	H4	G3	√	VREF
52	2	J5	F1	17	VREF
53	2	J4	H3	14	-
54	2	K5	H2	18	VREF
55	2	J3	K4	19	-
56	2	L5	K3	√	D1
57	2	L4	K2	√	D2
58	2	M5	L3	17	-
59	2	L1	M4	14	-
60	2	N5	M2	15	VREF
61	2	N4	N3	16	-
62	2	N2	P5	15	-
63	2	P4	P3	√	D3
64	2	P2	R5	17	-
65	2	R4	R3	14	-
66	2	R1	T4	18	VREF
67	2	T5	T3	19	VREF
68	2	T2	U3	√	-
69	3	U1	U2	19	VREF
70	3	V2	V4	18	VREF
71	3	V5	V3	14	-
72	3	W1	W3	17	-
73	3	W4	W5	√	VREF
74	3	Y3	Y4	15	-
75	3	AA1	Y5	16	-
76	3	AA3	AA4	15	VREF
77	3	AB3	AA5	14	-
78	3	AC1	AB4	17	-
79	3	AC3	AB5	√	D5
80	3	AC4	AD3	√	VREF
81	3	AE1	AC5	4	-
82	3	AD4	AF1	18	VREF
83	3	AF2	AD5	14	-
84	3	AG2	AE4	20	VREF
85	3	AH1	AE5	√	VREF
86	3	AF4	AJ1	15	-
87	3	AJ2	AF5	14	-
88	3	AG4	AK2	15	VREF
89	3	AJ3	AG5	14	-
90	3	AL1	AH4	14	VREF
91	3	AJ4	AH5	√	INIT
92	4	AL4	AJ6	√	-
93	4	AK5	AN3	8	VREF
94	4	AL5	AJ7	√	-
95	4	AM4	AM5	√	VREF
96	4	AK7	AL6	3	-
97	4	AM6	AN6	√	-
98	4	AL7	AJ9	√	VREF
99	4	AN7	AL8	9	VREF
100	4	AM8	AJ10	7	-
101	4	AL9	AM9	7	VREF
102	4	AK10	AN9	2	-
103	4	AL10	AM10	√	VREF
104	4	AL11	AJ12	√	-
105	4	AN11	AK12	8	-
106	4	AL12	AM12	√	-
107	4	AK13	AL13	√	VREF
108	4	AM13	AN13	3	-

Table 16: **FG256 Package — XCV50E, XCV100E, XCV200E, XCV300E**

Bank	Pin Description	Pin #
4	IO_L43P_Y	P12
4	IO_VREF_L43N_Y	R13[2]
4	IO_L44P_YY	N12
4	IO_L44N_YY	T13
4	IO_VREF_L45P_YY	T12
4	IO_L45N_YY	P11
4	IO_L46P_Y	R12
4	IO_L46N_Y	N11
4	IO_VREF_L47P_YY	T11[1]
4	IO_L47N_YY	M11
4	IO_L48P_YY	R11
4	IO_L48N_YY	T10
4	IO_L49P_Y	R10
4	IO_L49N_Y	M10
4	IO_VREF_L50P_Y	P9
4	IO_L50N_Y	T9
4	IO_L51P_Y	N10
4	IO_L51N_Y	R9
4	IO_LVDS_DLL_L52P	N9
5	GCK1	R8
5	IO	N7
5	IO	T7
5	IO_LVDS_DLL_L52N	T8
5	IO_L53P_Y	R7
5	IO_VREF_L53N_Y	P8
5	IO_L54P_Y	P7
5	IO_L54N_Y	T6
5	IO_L55P_YY	M7
5	IO_L55N_YY	R6
5	IO_L56P_YY	P6
5	IO_VREF_L56N_YY	R5[1]
5	IO_L57P_Y	N6
5	IO_L57N_Y	T5
5	IO_L58P_YY	M6
5	IO_VREF_L58N_YY	T4
5	IO_L59P_YY	T3
5	IO_L59N_YY	P5
5	IO_VREF_L60P_Y	T2[2]
5	IO_L60N_Y	N5
6	IO_L61N_YY	M3
6	IO_L61P_YY	R1
6	IO_L62N	M4
6	IO_VREF_L62P	N2[2]
6	IO_L63N_YY	L5
6	IO_L63P_YY	P1
6	IO_VREF_L64N_Y	N1
6	IO_L64P_Y	L3
6	IO_L65N	M2
6	IO_L65P	L4
6	IO_VREF_L66N_Y	M1[1]
6	IO_L66P_Y	K4
6	IO_L67N_YY	L2
6	IO_L67P_YY	L1
6	IO_L68N	K3
6	IO_L68P	K1
6	IO_L69N_YY	K2
6	IO_L69P_YY	K5
6	IO_VREF_L70N_Y	J3
6	IO_L70P_Y	J1
6	IO_L71N	J4
6	IO_L71P	H1
6	IO	J2
7	IO	C2
7	IO_L72N_YY	G1
7	IO_L72P_YY	H4
7	IO_L73N	G5
7	IO_L73P	H2

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
3	IO	Y26
3	IO	AB25
3	IO	AC25[1]
3	IO	AC26
3	IO_L69P_YY	P21
3	IO_L69N_YY	P23
3	IO_L70P_Y	P22
3	IO_VREF_L70N_Y	R25
3	IO_L71P_Y	P19
3	IO_L71N_Y	P20
3	IO_L72P_YY	R21
3	IO_L72N_YY	R22
3	IO_D4_L73P_YY	R24
3	IO_VREF_L73N_YY	R23
3	IO_L74P_Y	T24
3	IO_L74N_Y	R20
3	IO_L75P_Y	T22
3	IO_L75N_Y	U24
3	IO_L76P_Y	T23
3	IO_L76N_Y	U25
3	IO_L77P_Y	T21
3	IO_L77N_Y	U20
3	IO_L78P_YY	U22
3	IO_L78N_YY	V26
3	IO_L79P_YY	T20
3	IO_D5_L79N_YY	U23
3	IO_D6_L80P_YY	V24
3	IO_VREF_L80N_YY	U21
3	IO_L81P_YY	V23
3	IO_L81N_YY	W24
3	IO_L82P_Y	V22
3	IO_VREF_L82N_Y	W26[2]
3	IO_L83P_Y	Y25
3	IO_L83N_Y	V21
3	IO_L84P_YY	V20
3	IO_L84N_YY	AA26
3	IO_L85P_YY	Y24

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
3	IO_VREF_L85N_YY	W23
3	IO_L86P_Y	AA24
3	IO_L86N_Y	Y23
3	IO_L87P_Y	AB26
3	IO_L87N_Y	W21
3	IO_L88P_Y	Y22
3	IO_VREF_L88N_Y	W22
3	IO_L89P_Y	AA23
3	IO_L89N_Y	AB24
3	IO_L90P_YY	W20
3	IO_L90N_YY	AC24
3	IO_D7_L91P_YY	AB23
3	IO_INIT_L91N_YY	Y21
4	GCK0	AA14
4	IO	AC18
4	IO	AE15[1]
4	IO	AE20
4	IO	AE23
4	IO	AF14[1]
4	IO	AF16[1]
4	IO	AF18[1]
4	IO	AF21
4	IO	AF23[1]
4	IO_L92P_YY	AC22
4	IO_L92N_YY	AD26
4	IO_L93P_Y	AD23
4	IO_L93N_Y	AA20
4	IO_L94P_YY	Y19
4	IO_L94N_YY	AC21
4	IO_VREF_L95P_YY	AD22
4	IO_L95N_YY	AB20
4	IO_L96P	AE22
4	IO_L96N	Y18
4	IO_L97P	AF22
4	IO_L97N	AA19
4	IO_VREF_L98P_YY	AD21

FG680 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 23: **FG680 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	A20	C22	NA	IO_DLL_L29N
2	1	D21	A19	NA	IO_DLL_L29P
1	5	AU22	AT22	NA	IO_DLL_L155N
0	4	AW19	AT21	NA	IO_DLL_L155P
IO LVDS Total Pairs: 247, Asynchronous Output Pairs: 111					
0	0	A36	C35	5	-
1	0	B35	D34	5	VREF
2	0	A35	C34	√	-
3	0	B34	D33	√	VREF
4	0	A34	C33	3	-
5	0	B33	D32	3	-
6	0	D31	C32	√	-
7	0	C31	A33	√	VREF
8	0	B31	B32	5	-
9	0	D30	A32	5	VREF
10	0	C30	A31	√	-
11	0	D29	B30	√	VREF
12	0	C29	A30	2	-
13	0	B29	A29	2	-
14	0	A28	B28	√	VREF
15	0	B27	C28	√	-
16	0	A27	D27	5	-
17	0	B26	C27	5	-
18	0	C26	D26	√	-
19	0	D25	A26	√	VREF
20	0	C25	B25	3	-
21	0	D24	A25	3	-
22	0	B23	A24	√	-
23	0	A23	C24	√	VREF
24	0	B22	B24	5	-
25	0	A22	E23	5	-
26	0	B21	D23	√	-
27	0	A21	C23	√	VREF
28	0	B20	E22	2	-
29	1	A19	C22	NA	IO_LVDS_DLL
30	1	B19	C21	2	VREF
31	1	A18	C19	2	-
32	1	B18	D19	√	VREF
33	1	A17	C18	√	-
34	1	B17	D18	5	-
35	1	A16	E18	5	-
36	1	D17	C17	√	VREF
37	1	E17	B16	√	-
38	1	C16	A15	3	-
39	1	D16	B15	3	-
40	1	B14	A14	√	VREF
41	1	A13	C15	√	-
42	1	B13	D15	5	-
43	1	A12	C14	5	-
44	1	C13	D14	√	-
45	1	D13	B12	√	VREF
46	1	C12	A11	2	-
47	1	C11	B11	2	-
48	1	D11	A10	√	VREF
49	1	C10	B10	√	-
50	1	D10	A9	5	VREF
51	1	C9	B9	5	-

Table 23: **FG680 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
188	6	AP39	AP38	4	-
189	6	AN38	AN36	6	VREF
190	6	AN39	AN37	√	-
191	6	AM38	AM36	4	-
192	6	AL36	AM37	6	-
193	6	AL37	AM39	√	VREF
194	6	AK36	AL38	√	-
195	6	AK37	AL39	7	VREF
196	6	AJ36	AK38	4	-
197	6	AJ37	AK39	√	VREF
198	6	AH37	AJ38	√	-
199	6	AH38	AJ39	4	-
200	6	AG38	AH39	√	VREF
201	6	AG39	AG36	√	-
202	6	AF39	AG37	6	-
203	6	AE38	AF36	4	-
204	6	AF38	AF37	4	-
205	6	AE36	AE39	6	VREF
206	6	AE37	AD38	√	-
207	6	AD36	AD39	4	-
208	6	AC39	AC38	6	-
209	6	AB38	AD37	√	VREF
210	6	AB39	AC35	√	-
211	6	AA38	AC36	7	-
212	6	AA39	AC37	4	-
213	6	Y38	AB35	√	VREF
214	6	Y39	AB36	√	-
215	6	AA36	AB37	4	VREF
216	7	W38	AA37	√	-
217	7	V39	W37	4	VREF
218	7	U39	W36	√	-
219	7	U38	V38	√	VREF
220	7	T39	V37	4	-
221	7	T38	V36	7	-

Table 23: **FG680 Differential Pin Pair Summary XCV600E, XCV1000E, XCV1600E, XCV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
222	7	R39	V35	√	-
223	7	U36	U37	√	VREF
224	7	U35	R38	6	-
225	7	T37	P39	4	-
226	7	T36	P38	√	-
227	7	N38	N39	6	VREF
228	7	M39	R37	4	-
229	7	M38	R36	4	-
230	7	L39	P37	6	-
231	7	N37	P36	√	-
232	7	N36	L38	√	VREF
233	7	M37	K39	4	-
234	7	L37	K38	√	-
235	7	L36	J39	√	VREF
236	7	K37	J38	4	-
237	7	K36	H39	√	VREF
238	7	J37	H38	√	-
239	7	G38	G39	√	VREF
240	7	F39	J36	6	-
241	7	F38	H37	4	-
242	7	E39	H36	√	-
243	7	E38	G37	6	VREF
244	7	D39	G36	4	-
245	7	F36	D38	4	VREF
246	7	E37	D37	6	-

Notes:
1. AO in the XCV1000E, 1600E, 2000E.
2. AO in the XCV600E, 1000E, 1600E.
3. AO in the XCV600E, 1000E.
4. AO in the XCV1000E, 1600E.
5. AO in the XCV1000E, 2000E.
6. AO in the XCV600E, 1000E, 2000E.
7. AO in the XCV1000E.
8. AO in the XCV2000E.

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
1	IO_L57N_Y	D9
1	IO_VREF_L57P_Y	A12[2]
1	IO_L58N_Y	E9
1	IO_L58P_Y	C12
1	IO_L59N_YY	B12
1	IO_VREF_L59P_YY	D8
1	IO_L60N_YY	A11
1	IO_L60P_YY	E8
1	IO_L61N_Y	C7
1	IO_L61P_Y	A10
1	IO_L62N_Y	C6
1	IO_L62P_Y	B10
1	IO_L63N_YY	A9
1	IO_VREF_L63P_YY	B9
1	IO_L64N_YY	A8
1	IO_L64P_YY	E7
1	IO_L65N_Y	B8
1	IO_L65P_Y	C5
1	IO_L66N_Y	A7
1	IO_VREF_L66P_Y	A6
1	IO_L67N_Y	B7
1	IO_L67P_Y	D6
1	IO_L68N_Y	A5
1	IO_L68P_Y	C4
1	IO_WRITE_L69N_YY	B6
1	IO_CS_L69P_YY	E6
2	IO	H2
2	IO	H3
2	IO	J1
2	IO	K5
2	IO	M2
2	IO	N1
2	IO	R5
2	IO	U1
2	IO	U4
2	IO	W3

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
2	IO	Y3
2	IO	AA3
2	IO_DOUT_BUSY_L70P_YY	F5
2	IO_DIN_D0_L70N_YY	D2
2	IO_L71P_Y	E4
2	IO_L71N_Y	E2
2	IO_L72P_Y	D3
2	IO_L72N_Y	F2
2	IO_VREF_L73P_Y	E1
2	IO_L73N_Y	F4
2	IO_L74P	G2
2	IO_L74N	E3
2	IO_L75P_Y	F1
2	IO_L75N_Y	G5
2	IO_VREF_L76P_Y	G1
2	IO_L76N_Y	F3
2	IO_L77P_YY	G4
2	IO_L77N_YY	H1
2	IO_L78P_Y	J2
2	IO_L78N_Y	G3
2	IO_L79P_Y	H5
2	IO_L79N_Y	K2
2	IO_VREF_L80P_YY	H4
2	IO_L80N_YY	K1
2	IO_L81P_YY	L2
2	IO_L81N_YY	L3
2	IO_VREF_L82P_Y	L1[2]
2	IO_L82N_Y	J5
2	IO_L83P_Y	J4
2	IO_L83N_Y	M3
2	IO_VREF_L84P_YY	J3
2	IO_L84N_YY	M1
2	IO_L85P_YY	N2
2	IO_L85N_YY	K4
2	IO_L86P_Y	N3
2	IO_L86N_Y	K3
2	IO_VREF_L87P_YY	L5

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO	AJ40
6	IO	AL41
6	IO	AN38
6	IO	AN42
6	IO	AP41
6	IO	AR39
6	IO_L211N_YY	AV41
6	IO_L211P_YY	AV42
6	IO_L212N_Y	AW40
6	IO_L212P_Y	AU41
6	IO_L213N_Y	AV39
6	IO_L213P_Y	AU42
6	IO_VREF_L214N_Y	AT41
6	IO_L214P_Y	AU38
6	IO_L215N	AT42
6	IO_L215P	AV40
6	IO_L216N_Y	AR41
6	IO_L216P_Y	AU39
6	IO_VREF_L217N_Y	AR42
6	IO_L217P_Y	AU40
6	IO_L218N_YY	AT38
6	IO_L218P_YY	AP42
6	IO_L219N_Y	AN41
6	IO_L219P_Y	AT39
6	IO_L220N_Y	AT40
6	IO_L220P_Y	AM40
6	IO_VREF_L221N_YY	AR38
6	IO_L221P_YY	AM41
6	IO_L222N_YY	AM42
6	IO_L222P_YY	AR40
6	IO_VREF_L223N_Y	AL40[2]
6	IO_L223P_Y	AP38
6	IO_L224N_Y	AP39
6	IO_L224P_Y	AL42
6	IO_VREF_L225N_YY	AP40
6	IO_L225P_YY	AK40
6	IO_L226N_YY	AK41

Table 24: **FG860 — XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
6	IO_L226P_YY	AN39
6	IO_L227N_Y	AK42
6	IO_L227P_Y	AN40
6	IO_VREF_L228N_YY	AM38
6	IO_L228P_YY	AJ41
6	IO_L229N_YY	AJ42
6	IO_L229P_YY	AM39
6	IO_L230N_Y	AH40
6	IO_L230P_Y	AH41
6	IO_L231N_Y	AL38
6	IO_L231P_Y	AH42
6	IO_L232N_Y	AL39
6	IO_L232P_Y	AG41
6	IO_L233N	AK39
6	IO_L233P	AG40
6	IO_L234N_Y	AJ38
6	IO_L234P_Y	AG42
6	IO_VREF_L235N_Y	AF42
6	IO_L235P_Y	AJ39
6	IO_L236N_YY	AF41
6	IO_L236P_YY	AH38
6	IO_L237N_Y	AE42
6	IO_L237P_Y	AH39
6	IO_L238N_Y	AG38
6	IO_L238P_Y	AE41
6	IO_VREF_L239N_YY	AG39
6	IO_L239P_YY	AD42
6	IO_L240N_YY	AD40
6	IO_L240P_YY	AF39
6	IO_L241N_Y	AD41
6	IO_L241P_Y	AE38
6	IO_L242N_Y	AE39
6	IO_L242P_Y	AC40
6	IO_VREF_L243N_YY	AD38
6	IO_L243P_YY	AC41
6	IO_L244N_YY	AB42
6	IO_L244P_YY	AC38

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	VCCO_0	C12
NA	VCCO_1	B25
NA	VCCO_1	C19
NA	VCCO_1	M18
NA	VCCO_1	M17
NA	VCCO_1	L17
NA	VCCO_1	H17
NA	VCCO_1	L16
NA	VCCO_1	M16
NA	VCCO_2	F29
NA	VCCO_2	M28
NA	VCCO_2	P23
NA	VCCO_2	R20
NA	VCCO_2	P20
NA	VCCO_2	R19
NA	VCCO_2	N19
NA	VCCO_2	P19
NA	VCCO_3	AE29
NA	VCCO_3	W28
NA	VCCO_3	U23
NA	VCCO_3	U20
NA	VCCO_3	T20
NA	VCCO_3	V19
NA	VCCO_3	T19
NA	VCCO_3	U19
NA	VCCO_4	AJ25
NA	VCCO_4	AH19
NA	VCCO_4	W18
NA	VCCO_4	AC17
NA	VCCO_4	Y17
NA	VCCO_4	W17
NA	VCCO_4	W16
NA	VCCO_4	Y16
NA	VCCO_5	AJ6
NA	VCCO_5	Y15
NA	VCCO_5	W15
NA	VCCO_5	AC14

Table 26: **FG900 — XCV600E, XCV1000E, XCV1600E**

Bank	Pin Description	Pin #
NA	VCCO_5	Y14
NA	VCCO_5	W14
NA	VCCO_5	W13
NA	VCCO_5	AH12
NA	VCCO_6	AE2
NA	VCCO_6	V12
NA	VCCO_6	U12
NA	VCCO_6	T12
NA	VCCO_6	U11
NA	VCCO_6	T11
NA	VCCO_6	U8
NA	VCCO_6	W3
NA	VCCO_7	F2
NA	VCCO_7	R12
NA	VCCO_7	P12
NA	VCCO_7	N12
NA	VCCO_7	R11
NA	VCCO_7	P11
NA	VCCO_7	P8
NA	VCCO_7	M3
NA	GND	Y18
NA	GND	AH7
NA	GND	AK30
NA	GND	AJ30
NA	GND	B30
NA	GND	A30
NA	GND	AK29
NA	GND	AJ29
NA	GND	AC29
NA	GND	H29
NA	GND	B29
NA	GND	A29
NA	GND	AH28
NA	GND	V28
NA	GND	N28
NA	GND	C28

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	IO_L6P_YY	H10[5]
0	IO_L7N_Y	D7
0	IO_L7P_Y	B5
0	IO_L8N_Y	K12
0	IO_L8P_Y	E8
0	IO_L9N	B6[4]
0	IO_L9P	F9[5]
0	IO_L10N_YY	G10
0	IO_L10P_YY	C7
0	IO_VREF_L11N_YY	D8
0	IO_L11P_YY	B7
0	IO_L12N	H11[4]
0	IO_L12P	C8[5]
0	IO_L13N_Y	E9
0	IO_L13P_Y	B8
0	IO_VREF_L14N_Y	K13[2]
0	IO_L14P_Y	G11
0	IO_L15N	A8[4]
0	IO_L15P	F10[5]
0	IO_L16N_YY	C9
0	IO_L16P_YY	H12
0	IO_VREF_L17N_YY	D10
0	IO_L17P_YY	A9
0	IO_L18N_Y	F11
0	IO_L18P_Y	A10
0	IO_L19N_Y	K14
0	IO_L19P_Y	C10
0	IO_VREF_L20N_YY	H13
0	IO_L20P_YY	G12
0	IO_L21N_YY	A11
0	IO_L21P_YY	B11
0	IO_L22N_Y	E12
0	IO_L22P_Y	D11
0	IO_L23N_Y	G13

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
0	IO_L23P_Y	C12
0	IO_L24N_Y	K15
0	IO_L24P_Y	A12
0	IO_L25N_Y	B12
0	IO_L25P_Y	H14
0	IO_L26N_YY	D12
0	IO_L26P_YY	F13
0	IO_VREF_L27N_YY	A13
0	IO_L27P_YY	B13
0	IO_L28N_YY	J15[4]
0	IO_L28P_YY	G14[5]
0	IO_L29N_Y	C13
0	IO_L29P_Y	F14
0	IO_L30N_Y	H15
0	IO_L30P_Y	D13
0	IO_L31N	A14[4]
0	IO_L31P	K16[5]
0	IO_L32N_YY	E14
0	IO_L32P_YY	B14
0	IO_VREF_L33N_YY	G15
0	IO_L33P_YY	D14
0	IO_L34N	J16[4]
0	IO_L34P	D15[5]
0	IO_L35N_Y	F15
0	IO_L35P_Y	B15
0	IO_L36N_Y	A15
0	IO_L36P_Y	E15
0	IO_L37N	G16[4]
0	IO_L37P	A16[5]
0	IO_L38N_YY	F16
0	IO_L38P_YY	J17
0	IO_VREF_L39N_YY	C16
0	IO_L39P_YY	B16
0	IO_L40N_Y	H17

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6
NA	GND	H27

Table 28: **FG1156 — XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

Bank	Pin Description	Pin #
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16